

May 2001

FQP27P06

60V P-Channel MOSFET

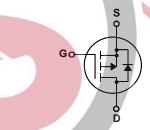
General Description

These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand a high energy pulse in the avalanche and commutation modes. These devices are well suited for low voltage applications such as automotive, DC/DC converters, and high efficiency switching for power management in portable and battery operated products.

Features

- -27A, -60V, $R_{DS(on)} = 0.07\Omega$ @V_{GS} = -10 V Low gate charge (typical 33 nC)
- Low Crss (typical 120 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating



GDS

TO-220 **FQP Series**

Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	FQP27P06	Units	
V_{DSS}	Drain-Source Voltage	-60	V	
I _D	Drain Current - Continuous (T _C = 25°C)	-27	А	
	- Continuous (T _C = 100°C)	-19.1	А	
I _{DM}	Drain Current - Pulsed (Note 1)	-108	A	
V _{GSS}	Gate-Source Voltage	± 25	V	
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	560	mJ	
I _{AR}	Avalanche Current (Note 1)	-27	А	
E _{AR}	Repetitive Avalanche Energy (Note 1)	12	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)	-7.0	V/ns	
P _D	Power Dissipation (T _C = 25°C)	120	W	
	- Derate above 25°C	0.8	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +175	°C	
T _L	Maximum lead temperature for soldering purposes,	300	°C	
_	1/8" from case for 5 seconds			

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.25	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-60			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, Referenced to 25°C		-0.06		V/°C
I _{DSS}	Zana Oata Vallana Basis Oassat	V _{DS} = -60 V, V _{GS} = 0 V			-1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = -48 V, T _C = 150°C			-10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = -25 V, V _{DS} = 0 V			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
On Cha	aracteristics					l
		$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	20		-4.0	V
V _{GS(th)}	Gate Threshold Voltage Static Drain-Source	VDS - VGS, ID230 μA	-2.0		-4.0	V
R _{DS(on)}	On-Resistance	$V_{GS} = -10 \text{ V}, I_D = -13.5 \text{ A}$		0.055	0.07	Ω
9 _{FS}	Forward Transconductance	V _{DS} = -30 V, I _D = -13.5 A (Note 4)		12.4		S
	ic Characteristics			T		
C _{iss}	Input Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$		1100	1400	pF –
C _{oss}	Output Capacitance	f = 1.0 MHz		510	660	pF -
C _{rss}	Reverse Transfer Capacitance			120	155	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -30 \text{ V}, I_{D} = -13.5 \text{ A},$	/	18	45	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$	/	185	380	ns
t _{d(off)}	Turn-Off Delay Time	1.G = 20 12	7-	30	70	ns
t _f	Turn-Off Fall Time	(Note 4, 5)	7	90	190	ns
Qg	Total Gate Charge	$V_{DS} = -48 \text{ V}, I_{D} = -27 \text{ A},$		33	43	n C
Q _{gs}	Gate-Source Charge	V _{GS} = -10 V		6.8	/	nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		18		nC
.		111 1 2 2				
Drain-S	Source Diode Characteristics at				-27	Α
	Maximum Continuous Drain-Source Diode Forward Current Maximum Pulsed Drain-Source Diode Forward Current				-108	A
I _{SM}		V _{GS} = 0 V, I _S = -27 A			-4.0	V
V _{SD}	Drain-Source Diode Forward Voltage Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = -27 \text{ A}$ $V_{GS} = 0 \text{ V, } I_{S} = -27 \text{ A,}$		105	-4.0	
	Neverse Recovery Time	VGS - U V, IS = -Z/ A,		105		ns

- Notes: Notes: Notes: A Repetitive Rating: Pulse width limited by maximum junction temperature 2. L = 0.9mH, I_{AS} = -27A, V_{DD} = -25V, R_G = 25 Ω , Starting T_J = 25°C 3. I_{SD} ≤ -27A, di/dt ≤ 300A/ μ s, V_{DD} ≤ BV $_{DSS}$, Starting T_J = 25°C 4. Pulse Test: Pulse width ≤ 300 μ s, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

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Typical Characteristics

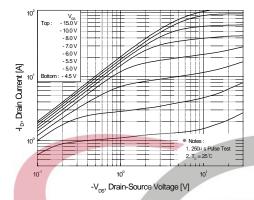


Figure 1. On-Region Characteristics

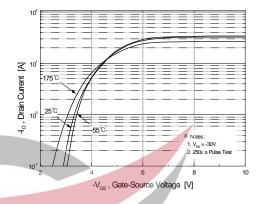


Figure 2. Transfer Characteristics

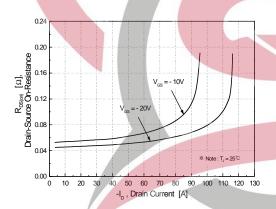


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

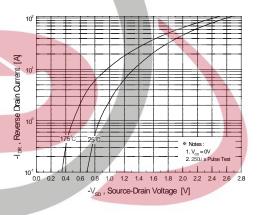


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

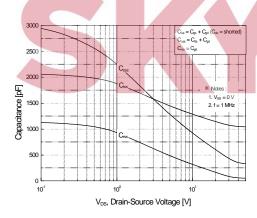


Figure 5. Capacitance Characteristics

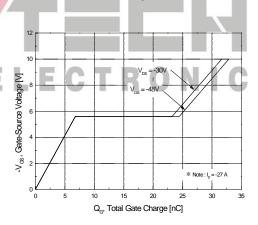


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)

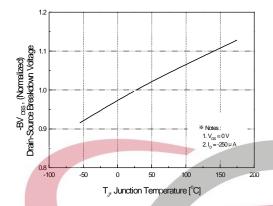
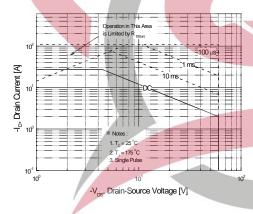


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



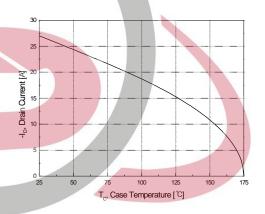


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

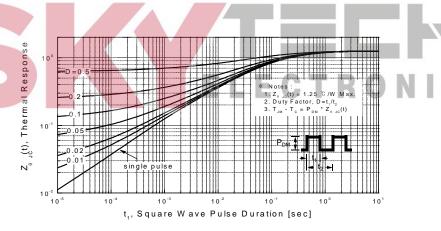
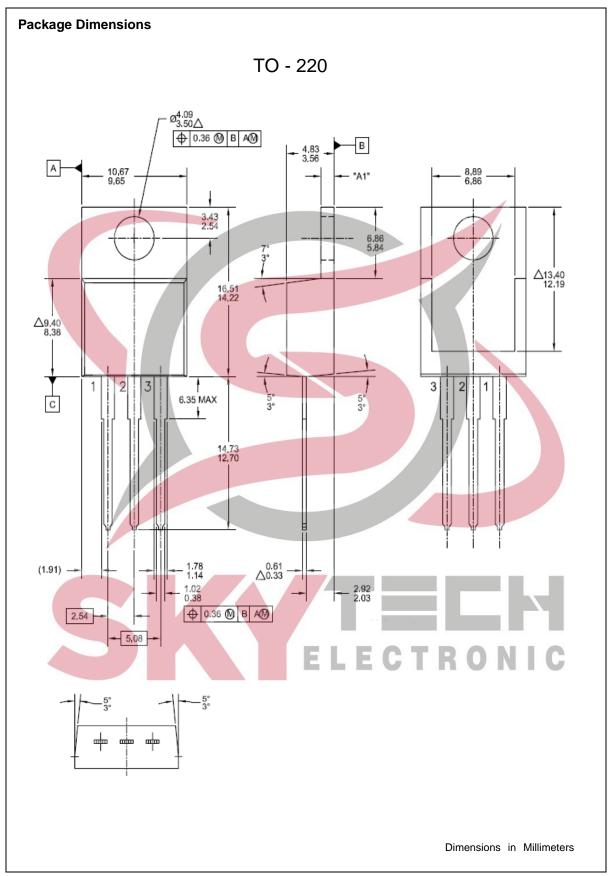


Figure 11. Transient Thermal Response Curve

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Gate Charge Test Circuit & Waveform V_{GS} Same Type as DUT -10V ≠V_{DS} DUT Charge Resistive Switching Test Circuit & Waveforms V_{DD} -10V DUT V_{DS}-Unclamped Inductive Switching Test Circuit & Waveforms BV_{DSS} BV_{DSS} - V_{DD} Time V_{DS} (t) V_{DD} + VDD DUT ${\rm I}_{\rm AS}$ $\mathsf{BV}_{\mathsf{DSS}}$

Peak Diode Recovery dv/dt Test Circuit & Waveforms DUT I_{SD} a Driver Compliment of DUT (N-Channel) V_{DD} √ V_{GS} • dv/dt controlled by R_G • I_{SD} controlled by pulse period Gate Pulse Width V_{GS} Gate Pulse Period 10V (Driver) **Body Diode Reverse Current** I_{SD} (DUT) I_{RM} di/dt I_{FM} , Body Diode Forward Current VDS (DUT) Body Diode Forward Voltage Drop Body Diode Recovery dv/dt



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